# International AUTOMOTIVE GRADE TOR Rectifier

# AUIRF3415

#### **Features**

- Advanced Planar Technology
- Low On-Resistance
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Timax
- Lead-Free, RoHS Compliant
- Automotive Qualified\*

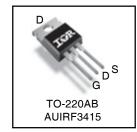
#### **Description**

Specifically designed for Automotive applications, this cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

## HEXFET® Power MOSFET



V <sub>(BR)DSS</sub>	3	150V
R <sub>DS(on)</sub>	max.	$0.042\Omega$
I <sub>D</sub>		43A



G	D	S
Gate	Drain	Source

## **Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature  $(T_A)$  is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	43	
I <sub>D</sub> @ T <sub>C</sub> = 100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	30	Α
I <sub>DM</sub>	Pulsed Drain Current ①	150	
P <sub>D</sub> @T <sub>C</sub> = 25°C	Power Dissipation	200	W
	Linear Derating Factor	1.3	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 20	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (Thermally Limited) <sup>②</sup>	590	mJ
I <sub>AR</sub>	Avalanche Current ①	22	Α
E <sub>AR</sub>	Repetitive Avalanche Energy ①	20	mJ
dv/dt	Peak Diode Recovery dv/dt 3	5.0	V/ns
$T_J$	Operating Junction and	-55 to + 175	
T <sub>STG</sub>	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

#### Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ®		0.75	
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.50		°C/W
$R_{\theta JA}$	Junction-to-Ambient		62	

HEXFET® is a registered trademark of International Rectifier.

<sup>\*</sup>Qualification standards can be found at http://www.irf.com/

## Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	150			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.17		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			0.042	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 22A ⊕
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
gfs	Forward Transconductance	19			S	$V_{DS} = 50V, I_D = 22A$
I <sub>DSS</sub>	Drain-to-Source Leakage Current			25	μΑ	$V_{DS} = 150V, V_{GS} = 0V$
				250		$V_{DS} = 120V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-100		V <sub>GS</sub> = -20V

## Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$Q_g$	Total Gate Charge			200		I <sub>D</sub> = 22A
$Q_{gs}$	Gate-to-Source Charge			17	nC	V <sub>DS</sub> = 120V
$Q_{gd}$	Gate-to-Drain ("Miller") Charge			98		V <sub>GS</sub> = 10V, See Fig. 6 & 13 <sup>⊕</sup>
t <sub>d(on)</sub>	Turn-On Delay Time		12			$V_{DD} = 75V$
t <sub>r</sub>	Rise Time		55		1	$I_D = 22A$
t <sub>d(off)</sub>	Turn-Off Delay Time		71		ns	$R_G = 2.5 \Omega$
t <sub>f</sub>	Fall Time		69		1	$R_D = 3.3 \Omega$ , See Fig. 10
$L_D$	Internal Drain Inductance		4.5			Between lead,
					nH	6mm (0.25in.)
Ls	Internal Source Inductance	_	7.5		1	from package G
						and center of die contact
C <sub>iss</sub>	Input Capacitance		2400			$V_{GS} = 0V$
Coss	Output Capacitance	_	640		pF	$V_{DS} = 25V$
C <sub>rss</sub>	Reverse Transfer Capacitance		340			f = 1.0MHz, See Fig. 5

### **Diode Characteristics**

	Parameter	Min.	Тур.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current			43		MOSFET symbol
	(Body Diode)				Α	showing the
I <sub>SM</sub>	Pulsed Source Current			150		integral reverse
	(Body Diode) ①					p-n junction diode.
$V_{SD}$	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C$ , $I_S = 22A$ , $V_{GS} = 0V$ ④
t <sub>rr</sub>	Reverse Recovery Time		260	390		$T_J = 25^{\circ}C$ , $I_F = 22A$
$Q_{rr}$	Reverse Recovery Charge		2.2	3.3	nC	di/dt = 100A/μs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsio	turn-or	time is	negligib	le (turn-on is dominated by LS+LD)

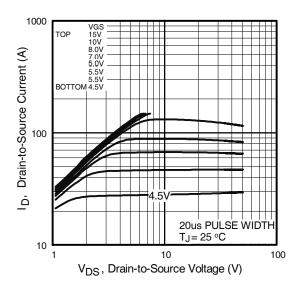
#### Notes:

- $^{\scriptsize \textcircled{1}}$  Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- $\label{eq:loss_spin_spin} \begin{tabular}{ll} $\mathbb{J}_{SD} \leq 22A, \ di/dt \leq 820A/\mu s, \ V_{DD} \leq V_{(BR)DSS}, \\ $T_J \leq 175^\circ C$ \end{tabular}$
- 4 Pulse width  $\leq 300 \mu s$ ; duty cycle  $\leq 2\%$ .
- $\ ^{\textcircled{5}}$  R  $_{\theta}$  is measured at TJ approximately 90°C.

## Qualification Information<sup>†</sup>

		Automotive				
Qualification Level			(per AEC-Q101) <sup>††</sup>			
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.				
Moisture Se	Sensitivity Level TO-220 N/A		N/A			
	Machine Model	Class M4 (+/- 800V) <sup>†††</sup>				
		AEC-Q101-002				
ECD	Human Body Model	Class H2 (+/- 3500V) <sup>†††</sup>				
ESD		AEC-Q101-001				
	Charged Device	Class C5 (+/- 2000V) <sup>†††</sup>				
	Model	AEC-Q101-005				
RoHS Com	S Compliant Yes		Yes			

- † Qualification standards can be found at International Rectifier's web site: http://www.irf.com/
- †† Exceptions to AEC-Q101 requirements are noted in the qualification report.
- ††† Highest passing voltage.



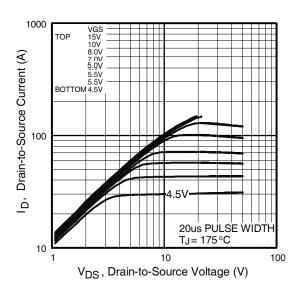
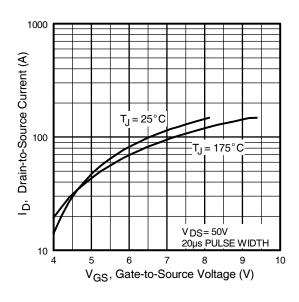


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics



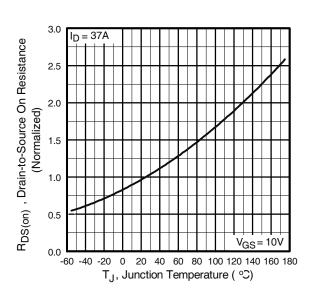
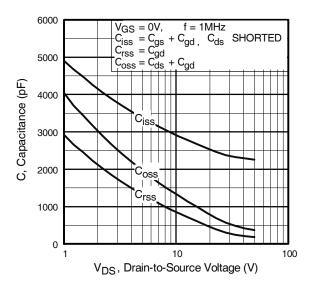
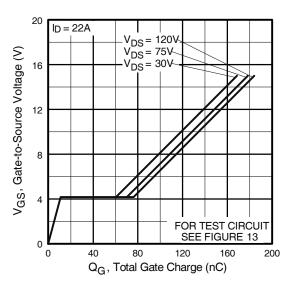


Fig 3. Typical Transfer Characteristics

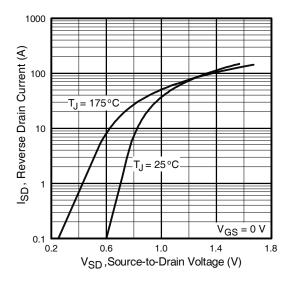
**Fig 4.** Normalized On-Resistance Vs. Temperature





**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage

**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



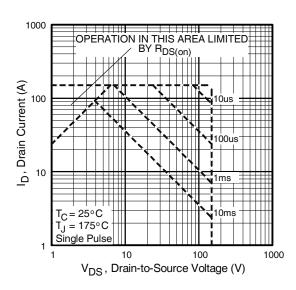


Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area

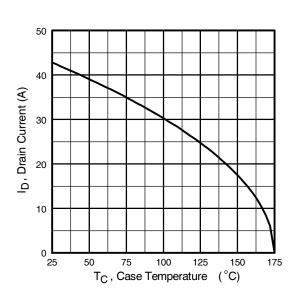


Fig 9. Maximum Drain Current Vs.
Case Temperature

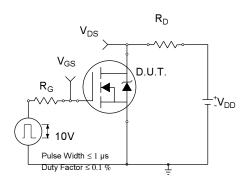


Fig 10a. Switching Time Test Circuit

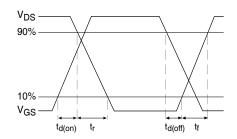


Fig 10b. Switching Time Waveforms

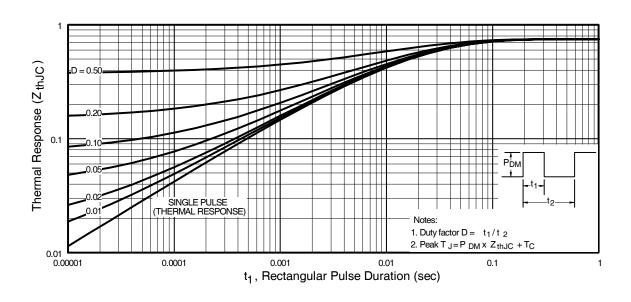


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

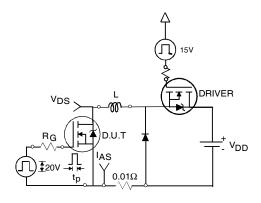


Fig 12a. Unclamped Inductive Test Circuit

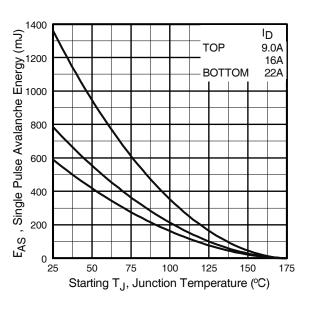


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

V(BR)DSS

Fig 12b. Unclamped Inductive Waveforms

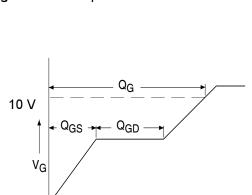


Fig 13a. Basic Gate Charge Waveform

Charge -

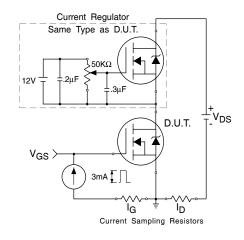
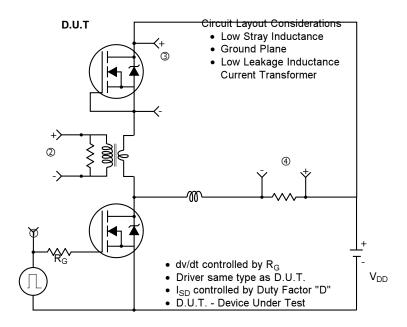
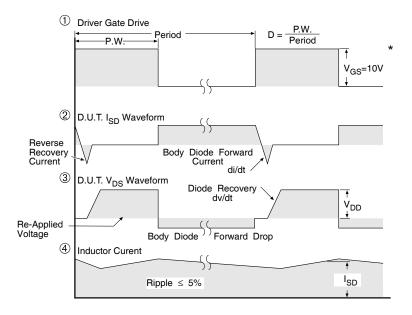


Fig 13b. Gate Charge Test Circuit

## Peak Diode Recovery dv/dt Test Circuit



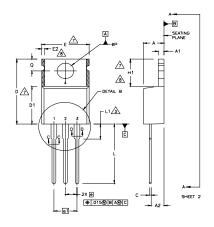


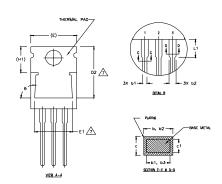
<sup>\*</sup> V<sub>GS</sub> = 5V for Logic Level Devices

Fig 14. For N-Channel HEXFETS

## TO-220AB Package Outline

Dimensions are shown in millimeters (inches)





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5 M— 1994,
  DIMENSIONING ARE SHOWN IN INCHES [MILLIMETERS],
  LEAD DIMENSION AND FINISH UNCONTROLLED IN L1,
  DIMENSION D & E DO NOT INCLUDE MOLD FLASH, MOLD FLASH
  SHALL NOT EXCEED .005" (0.127) PER SIDE, THESE DIMENSIONS ARE
  MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY,
  DIMENSION 1 & c1 APPLY TO BASE METAL ONLY,
  CONTROLLING DIMENSION: INCHES.
  THERMAL PAGE CONTIOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
  DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING
  AND SINGULATION IRREGULARITIES ARE ALLOWED.

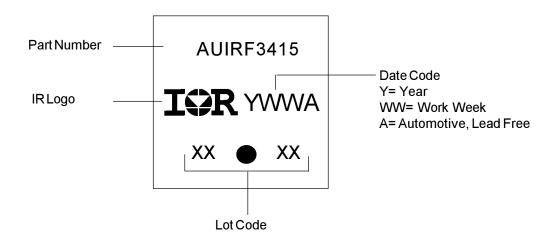
# HEXFET IGBTs. CoPACK

- 1.- GATE 2.- COLLECTOR 3.- EMITTER
- DIODES

14				
MILLIM	ETERS	INCHES		
MIN.	MAX.	MIN.	MAX.	NOTES
3.56	4.82	.140	.190	
0.51	1.40	.020	.055	
2,04	2,92	.080	.115	
0.38	1,01	,015	.040	
0.38	0.96	.015	.038	5
1,15	1,77	.045	.070	
1.15	1.73	.045	.068	
0,36	0.61	.014	.024	
0,36	0.56	.014	.022	5
14,22	16.51	.560	.650	4
8.38	9.02	.330	.355	
12,19	12.88	.480	.507	7
9,66	10,66	.380	.420	4,7
8.38	8.89	.330	.350	7
2.54 BSC		.100	BSC	1
5.0	38	.200	BSC	
5.85	6.55	.230	.270	7,8
12.70	14,73	.500	.580	
-	6.35	-	.250	3
3,54	4.08	.139	.161	
2,54	3,42	,100	,135	
90"-	-93*	90"	90 -93	
	3.56 0.51 2.04 0.38 0.38 1.15 1.15 0.36 0.36 14.22 8.38 12.19 9.66 8.38 2.54 5.1 5.2 5.2 5.2 5.2 5.2 5.2 5.2 5.2 5.2 5.2	3.56 4.82 0.51 1.40 2.04 2.92 0.88 1.01 0.38 0.96 1.15 1.77 1.15 1.73 0.36 0.61 0.36 0.56 14.22 16.51 8.38 9.02 12.19 12.88 9.66 10.66 8.38 8.89 2.54 BSC 5.08 5.08 5.85 6.55 12.70 14.73 - 6.35 3.54 4.08	3.56 4.82	3.56 4.82 .140 .190 .055

DIMENSIONS

# TO-220AB Part Marking Information



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

# **Ordering Information**

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRF3415	TO-220	Tube	50	AUIRF3415

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